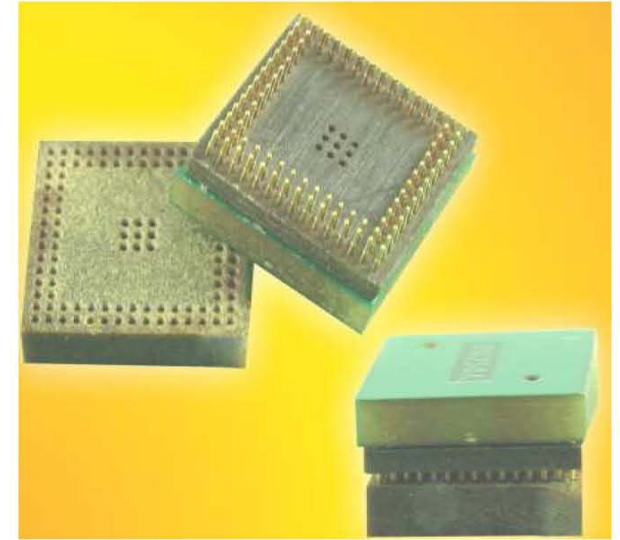




**Ironwood  
Electronics, Inc.**



**0.5mm, 0.65mm  
Pitch Giga-snaP™**  
Emulation, System Development,  
Field Upgrade, Production  
Socket Adapters



**High Performance  
IC Sockets And  
Test Adaptors**

# Application Need



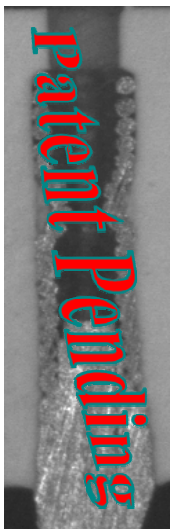
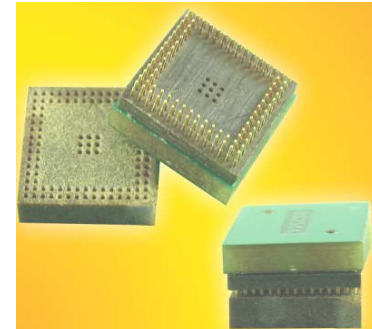
- *In-circuit emulation of a system board that has 0.5mm and 0.65mm pitch array pattern.*
- *Test and debug of a system development board that has 0.5mm and 0.65mm pitch area array devices such as BGA, LGA.*
- *Debugging production board that has 0.5mm and 0.65mm pitch area array devices such as BGA, LGA.*
- *Reworking 0.5mm and 0.65mm pitch BGA devices by removing from the board (both development and production) and reattaching to the target land pattern.*
- *Upgrading production systems that has 0.5mm and 0.65mm pitch BGA devices.*

# Solution – Chip Size Adapters

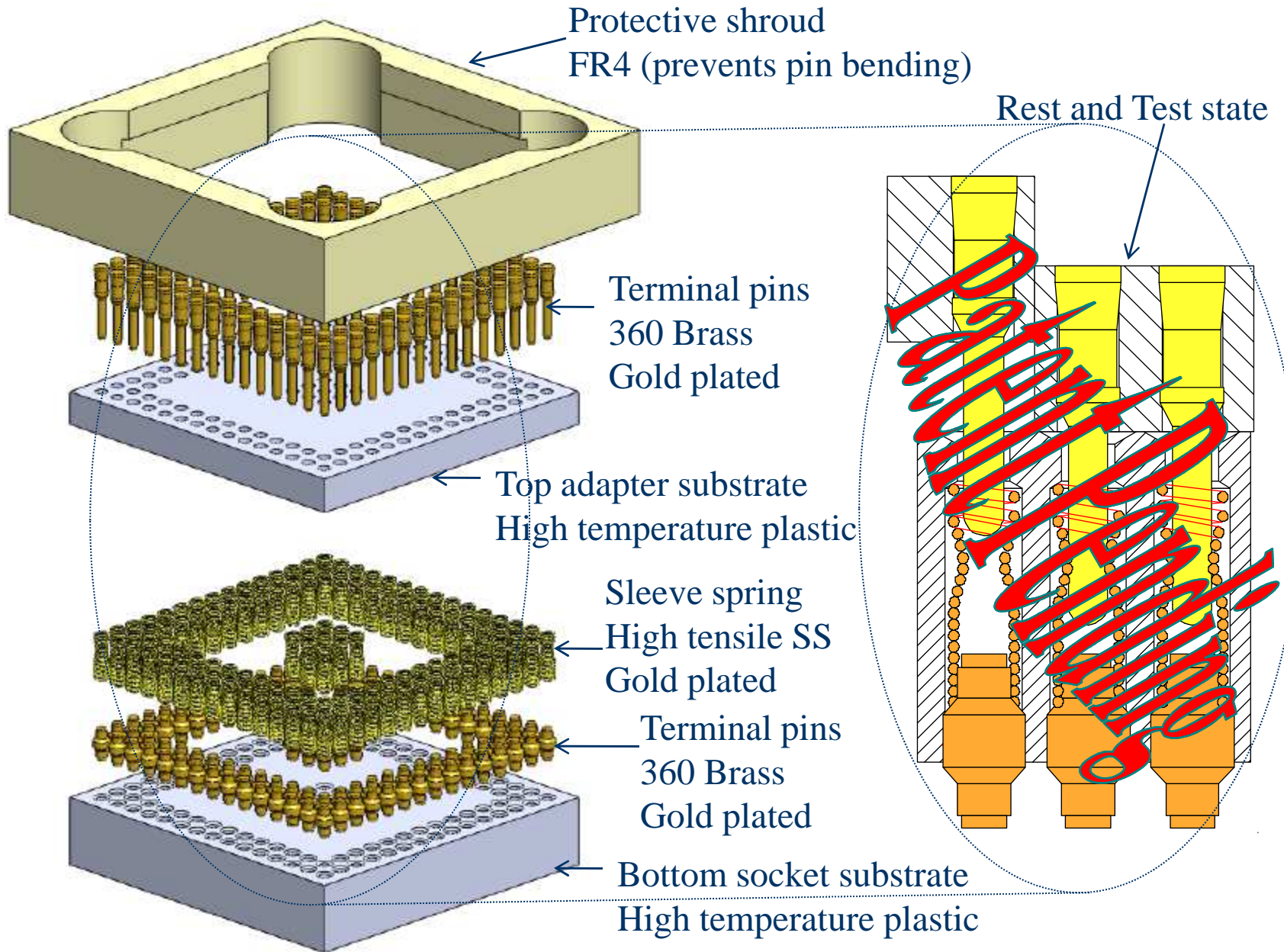


## Plug and Play Giga-snaP™ Adapters

- An economical and reliable alternative to soldering BGA devices directly to the motherboard.
- Same footprint as BGA device.
- Compact, low-profile design maximizes PC board space in system development.
- Soldering very similar to IC package using conventional methodology and no external hardware required.
- RoHS compliant materials.
- PCB can be reflowed with Giga-snaP™ assembled (withstands multiple reflow cycles).
- Access to BGA pads for in-circuit emulation, test and interconnection.
- Connection via Gold plated terminals that has optimized insertion/extraction force for reliability and robustness.
- Shortest interconnect length enables high speed applications.

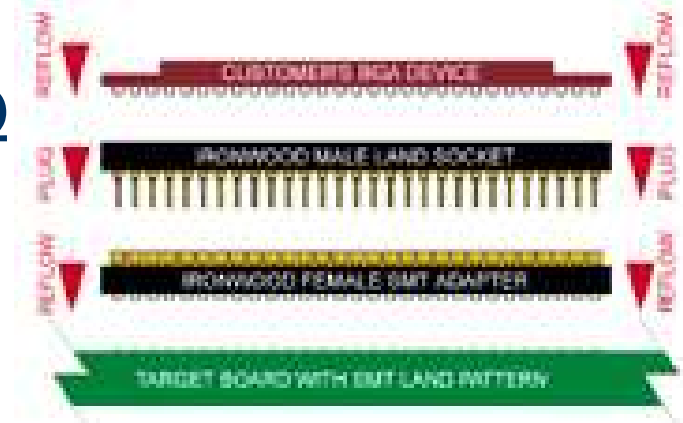


# Giga-snaP™ Interconnect

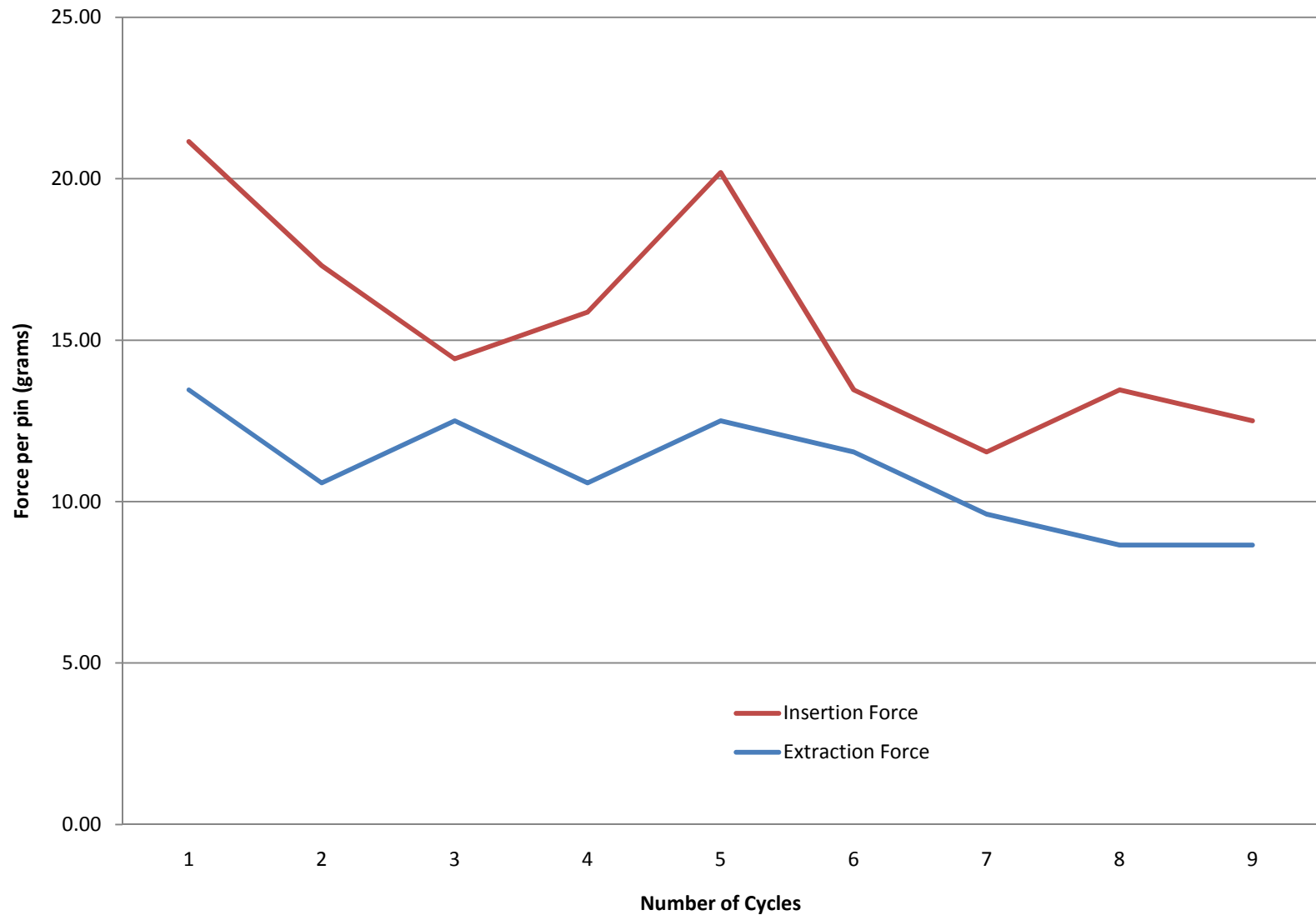


# 0.5mm Pitch Giga-snaP™ Contact Typical Characteristics

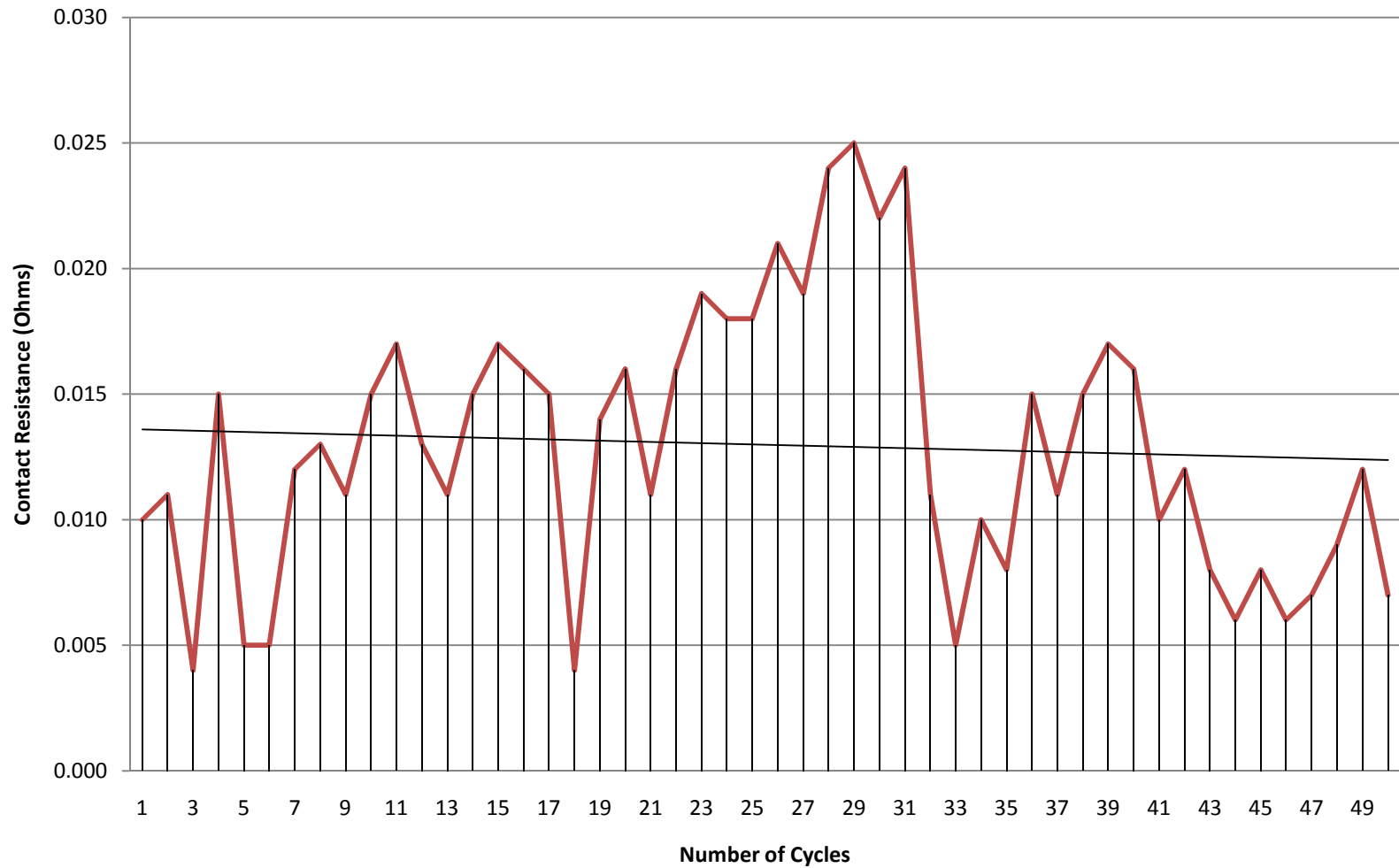
- Contact resistance < 15 mΩ
- Self Inductance <1.4nH
- Bandwidth >7GHz @-1dB
- Mutual Capacitance <0.2pF
- Insertion force 20grams per pin
- Extraction force 15grams per pin
- Operating temperature -55 to +150° C
- Insertion/Extraction cycles >100
- Current rating 1A per contact



## Insertion and Extraction Force Data



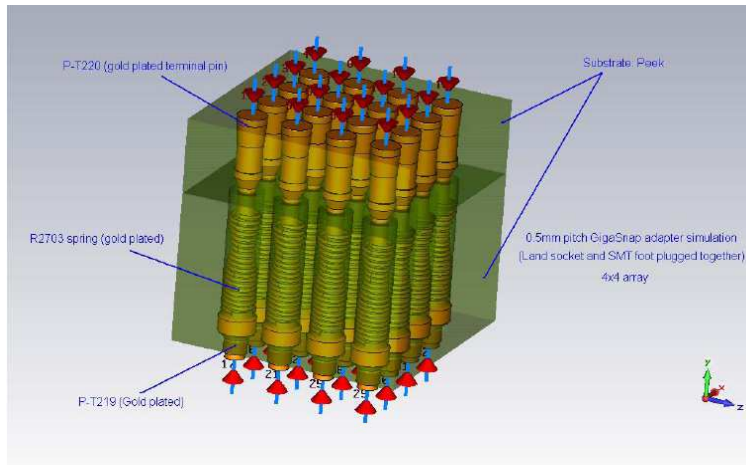
## Contact Resistance Data



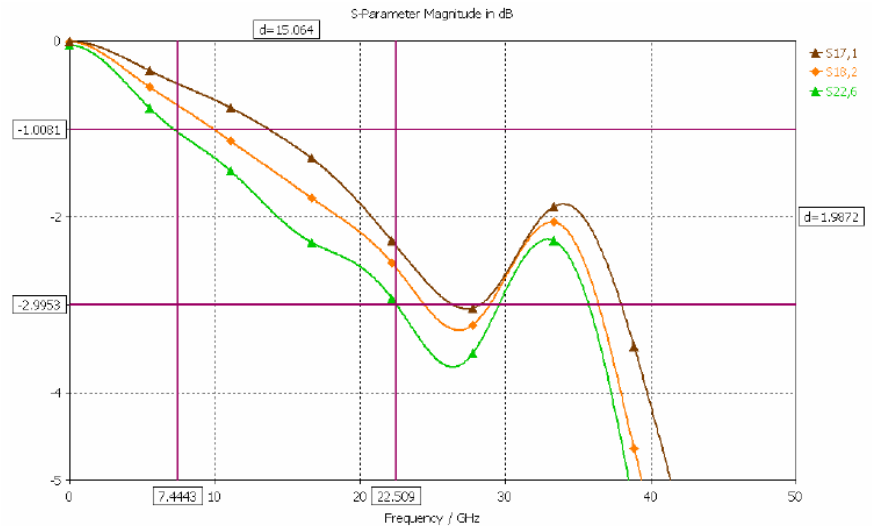
# Electrical Characterization



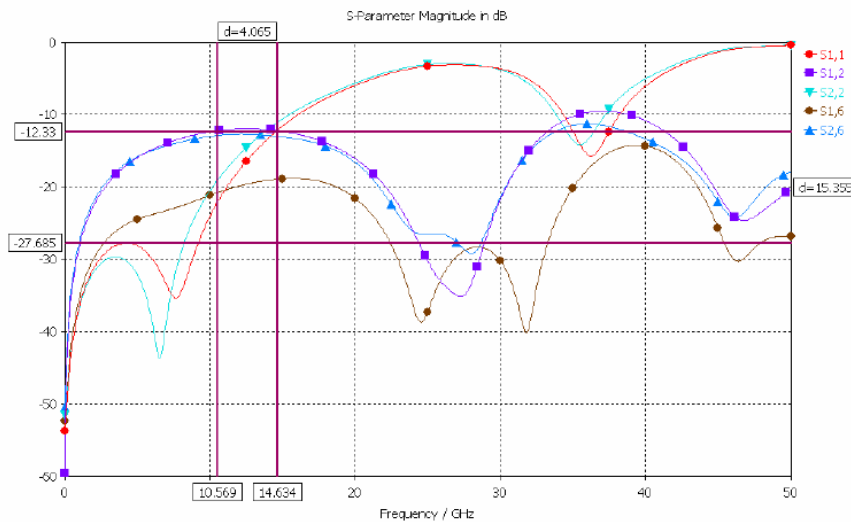
## Product Model



## Bandwidth Data



## Return loss & Cross talk



## Mutual Capacitance

0.197	0.132	0.132	0.197
0.132	0.034	0.034	0.132
0.102	0.034	0.034	0.132
0.197	0.132	0.132	0.197

## Mutual Inductance

Pin1	$L_{12}=0.0333$	$L_{13}=0.01153$	$L_{14}=0.00393$
$L_{56}=0.3994$	Pin6	$L_{67}=0.4160$	$L_{68}=0.1560$
$L_{911}=0.1546$	$L_{1011}=0.4160$	Pin11	$L_{1112}=0.3994$
$L_{1316}=0.0392$	$L_{1416}=0.1152$	$L_{1516}=0.3372$	Pin16

# High Volume Manufacturing



## Pick & Place SMT Line, Reflow Oven



## Stencil/Screen Printer, Tape & Reel Packaging



## CNC & Screw Machines



## Optical Inspection Unit



# Value Proposition



- Proven solution for automobile applications due to extreme temperature capability.
- Shortest electrical path, proven solution for high speed digital and RF applications (excellent bandwidth >7GHz).
- Reliable and Robust due to low and stable contact resistance throughout life cycle.
- Low insertion and extraction force for ease of operation.
- Complete automation using SolidWorks® CAD, GibbsCAM® and High speed CNC & screw machines for component fabrication.
- Complete automation of pin loading, assembly and inspection of Giga-snap™ product.
- Full traceability built into process.
- Established lean/six sigma process eliminates non-value added steps in the manufacturing sequence which enables low cost for end customers.
- Established “Pull” system and “Kanban” allow flexible manufacturing flow which enables short lead time for various order sizes.
- Pick & Place, Tape & Reel support for end users.
- No substrate warping, No CTE mismatch, Co-planarity <100µm.
- Component heat dissipation does not affect solder connection.
- Solders same as the IC it emulates.



Tack	Obrigado	Vielen Dank
Merci	ありがとうございます	
Bedankt	Takk	感謝您
谢谢	Grazie	
	Спасибо	Thank You
Kiitos	Tak	
	Gracias	감사합니다
Dziękujemy		Σας ευχαριστούμε

**Email:** [bce@bce.it](mailto:bce@bce.it)

**Website:** [www.bce.it](http://www.bce.it)